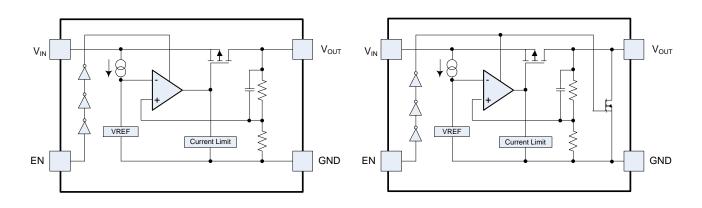


Pin Descriptions

Pin Number	Pin Name	Function		
1	l FN	Channel enable pin. This pin should be driven either high or low and must not be floating. Driving this pin high enables regulator output, while pulling it low enable regulator into shutdown mode.		
2	GND	Ground		
3	Vouт	Output voltage pin		
4	Vin	Power input pin		

Functional Block Diagram



AP7350 (Without Discharge)

AP7350D (With Discharge)

Absolute Maximum Ratings (Note 6)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	4	kV
ESD MM	Machine Model ESD Protection	400	V
Vin	Input Voltage	6.0	V
VEN	Input Voltage at EN pin	6.0	V
Vout	Output Voltage to GND	-0.3 to V _{IN} +0.3	V
TA	Operating Ambient Temperature	-40 to +85	°C
TJ	Maximum Junction Temperature	+125	°C
T _{STG}	Storage Temperature	-55 to +125	°C
PD	Power Dissipation (Note 7)	315	mW

Notes:

^{6.} Stresses beyond those listed under *Absolute Maximum Ratings* can cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods can affect device reliability.

^{7.} This is based on an application temperature of +40°C. Derate 3.75mW per °C for each degree above +40°C.



Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
Vin	Input Voltage	2.0	5.25	V
Іоит	Output Current	0	150	mA
TA	Operating Ambient Temperature	-40	+85	°C

Electrical Characteristics (@TA = +25°C, VEN = VIN = 5.0V (VOUT > 4.0V), VEN = VIN = VOUT+1V (1.5V < VOUT \leq 4.0V), VEN = VIN = 2.5V (VOUT \leq 1.5V), IOUT = 1mA, CIN = COUT = 0.1µF, unless otherwise specified.)

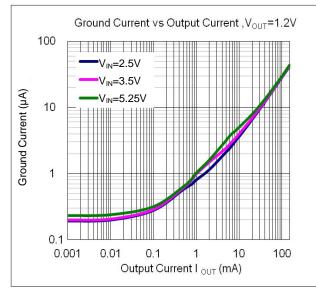
Parameter	Conditions		Min	Тур	Max	Unit
Input Voltage	T _A = -40°C to +85°C		2.0	_	5.25	V
	Vout > 2.0V	T _A = +25°C	-1	_	+1	%
Outrot Wallana Assura	Iout = 1mA	$T_A = -40^{\circ}C$ to $+85^{\circ}C$	-2	_	+2	
Output Voltage Accuracy	Vout ≤ 2.0V	T _A = +25°C	-40	1	40	mV
	I _{OUT} = 1mA	$T_A = -40^{\circ}C$ to $+85^{\circ}C$	-80	I	80	
Line Regulation (ΔVουτ/ΔVιΝ/Vουτ)	MAX (Vout + 1.0V, 2	$2.5V) \le V_{IN} \le 5.0V$	_	0.02	0.1	%/V
Load Decidation (AV)	$1 \text{mA} \le I_{\text{OUT}} \le 150 \text{mA}$	A (all versions except 4.5V)	-25	1	25	mV
Load Regulation (∆V _{ОUТ})	$1mA \le I_{OUT} \le 150mA$	A (applicable to 4.5V version)	-45		45	mV
Short Circuit Current Limit (Note 8)	V _{OUT} = 0V		_	60	_	mA
Octobrond Octobrond (Nieto O)) Om A	T _A = +25°C	_	0.25	0.4	μΑ
Quiescent Current (Note 9)	I _{OUT} = 0mA	$T_A = -40$ °C to $+85$ °C	_	_	0.7	μA
Standby Current (ISTANDBY)	Set EN low, No load		_	0.02	0.2	μA
Output Current	VIN ≥ VOUT + VDROPO	DUT	150	_	_	mA
		Vout = 1.2V	_	0.60	0.90	V
		Vout = 1.5V	_	0.43	0.75	
	I _{OUT} = 150mA	Vout = 1.8V	_	0.33	0.60	
		V _{OUT} = 1.85V	_	0.32	0.58	
		$V_{OUT} = 2.3V$	_	0.25	0.51	
Dropout Voltage (Note 10)		V _{OUT} = 2.5V	_	0.22	0.48	
		Vout = 2.7V	_	0.21	0.44	
		Vout = 2.8V	_	0.19	0.40	
		Vout = 3.0V	_	0.18	0.35	
		Vout = 3.3V	_	0.16	0.35	
		$V_{OUT} = 4.5V$	_	0.14	0.35	
Thermal Resistance Junction-to-Ambient (θ_{JA}) (Note 11)	Package: X2-WLB0606-4		_	267	_	°C/W
EN Input Low Voltage	_		_	_	0.4	V
EN Input High Voltage	_		1.0	_	5.25	V
Active Output Discharge Resistance (Note 12)	V _{IN} = 4.0V, V _{EN} = 0V		_	35	_	Ω

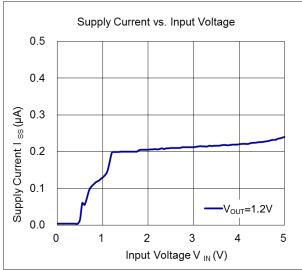
Notes:

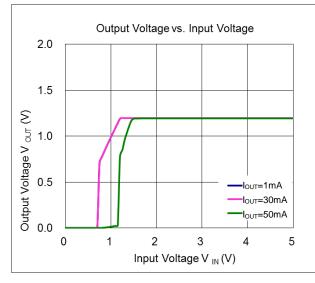
- 8. Short circuit current is measured with V_{OUT} pulled to GND.
- 9. Quiescent current defined here is the difference in current between the input and the output.
- 10. Dropout voltage is the voltage difference between the input and the output at which the output voltage drops 2% below its nominal value.
- 11. Test condition: X2-WLB0606-4 is mounted on PCB (compliant with JEDEC standard).
- 12. AP7350 is available with 2 options: built-in discharge (AP7350D) and non-discharge (AP7350).

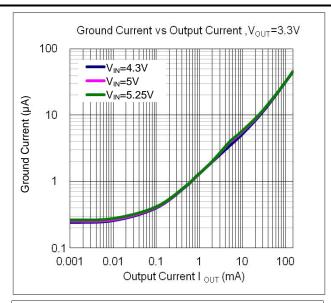


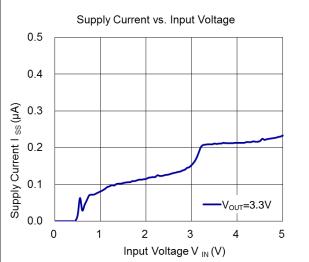
Performance Characteristics

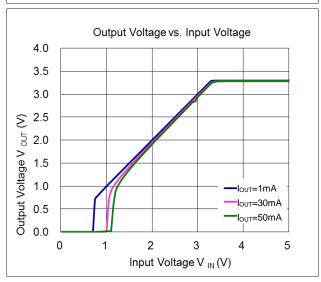




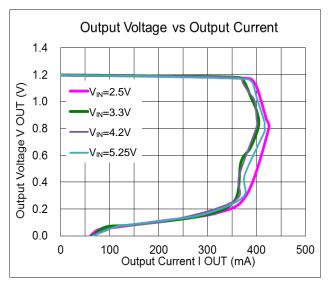


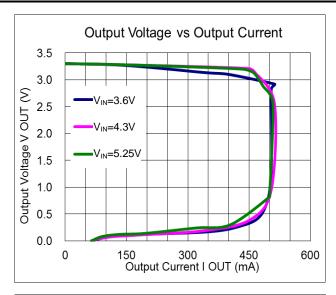


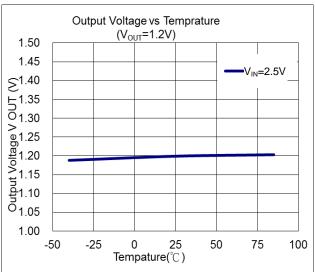


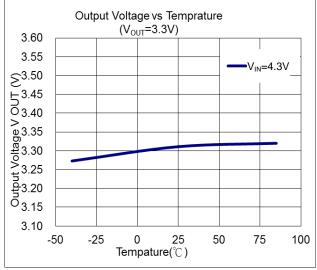


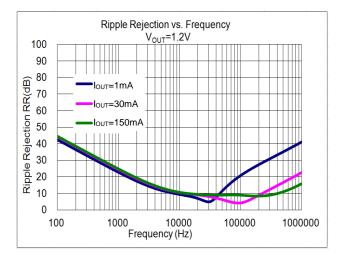


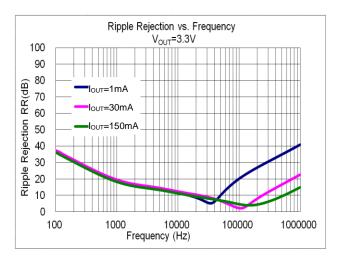




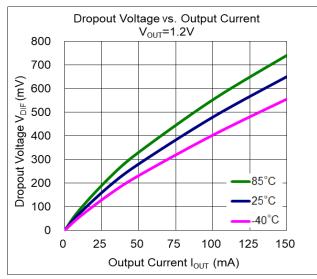


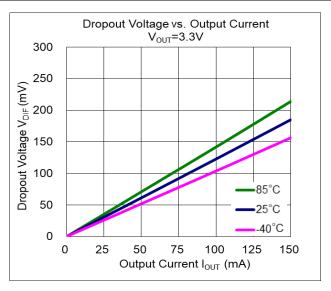


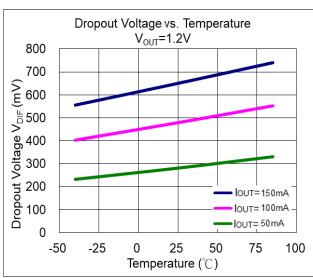


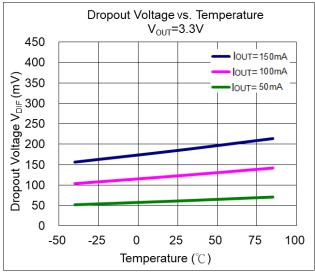




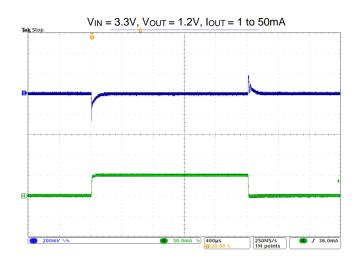


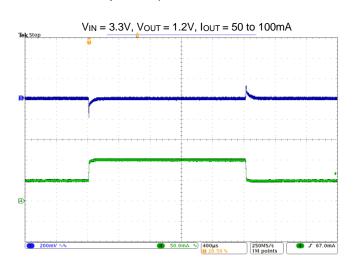






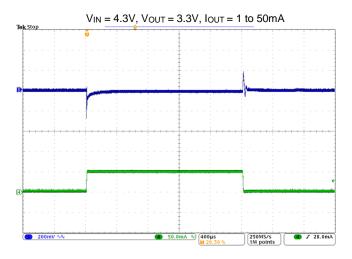
Load Transient Response ($C_{IN} = C_{OUT} = 0.1 \mu F$, $t_R = t_F = 5.0 \mu s$, unless otherwise specified.)

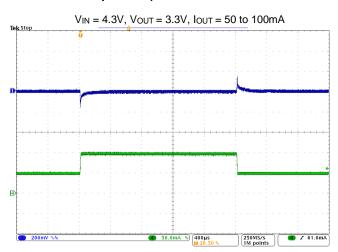




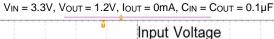


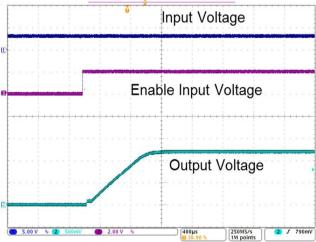
Load Transient Response ($C_{IN} = C_{OUT} = 0.1 \mu F$, $t_R = t_F = 5.0 \mu s$, unless otherwise specified.)

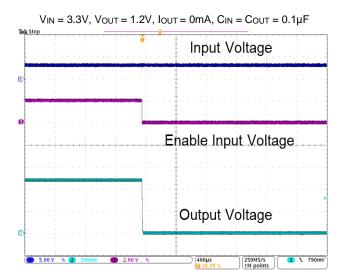




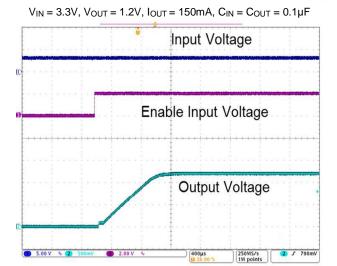
Turn On

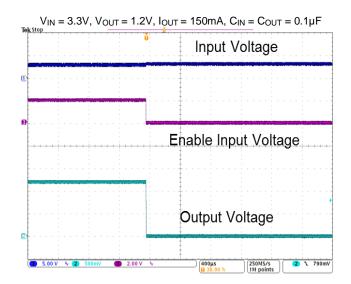






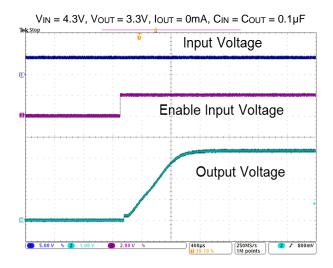
Turn Off



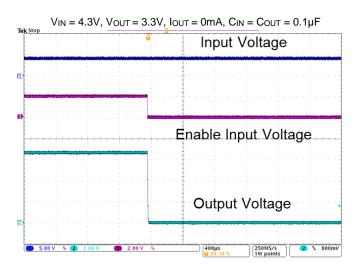


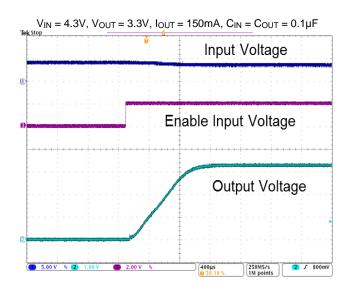


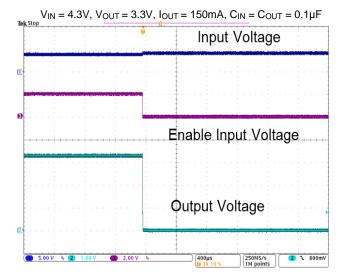
Turn On



Turn Off









Application Information

Output Capacitor

An output capacitor (Cout) is needed to improve transient response and maintain stability. The AP7350 is stable with very small ceramic output capacitors. The ESR (Equivalent Series Resistance) and capacitance drive the selection. If the application has large load variations, it is recommended to utilize low-ESR bulk capacitors. It is recommended to place ceramic capacitors as close as possible to the load and the GND pin and care should be taken to reduce the impedance in the layout.

Input Capacitor

To prevent the input voltage from dropping during load steps, it is recommended to utilize an input capacitor (C_{IN}). A minimum 0.1µF ceramic capacitor is recommended between V_{IN} and GND pin to decouple input power supply glitch. This input capacitor must be located as close as possible to the device to assure input stability and reduce noise. For PCB layout, a wide copper trace is required for both V_{IN} and GND pin.

Enable Control

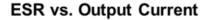
The AP7350 is turned on by setting the EN pin high, and is turned off by pulling it low. If this feature is not used, the EN pin should be tied to V_{IN} pin to keep the regulator output on at all time. To ensure proper operation, the signal source used to drive the EN pin must be able to swing above and below the specified turn-on/off voltage thresholds listed in the *Electrical Characteristics* section.

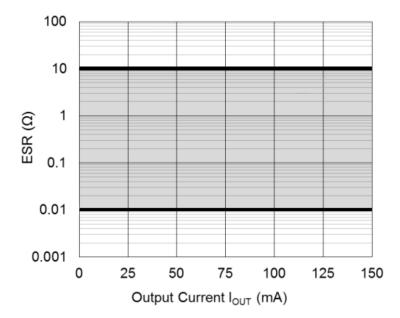
Layout Considerations

For good ground loop and stability, the input and output capacitors should be located close to the input, output, and GND pin of the device. The regulator GND pin should be connected to the external circuit ground to reduce voltage drop caused by trace impedance. Ground plane is generally used to reduce trace impedance. Wide trace should be used for large current paths from V_{IN} to V_{OUT}, and load circuit.

ESR vs. Output Current

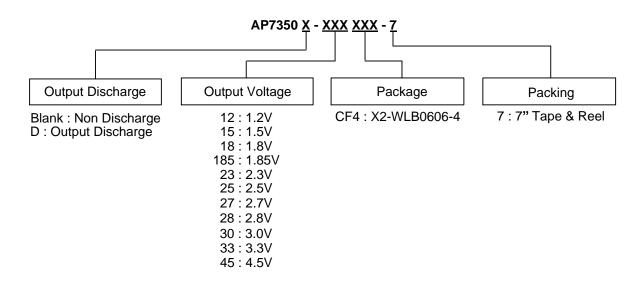
A ceramic type output capacitor is recommended for this series; however, the other output capacitors with low ESR also can be used. The relations between I_{OUT} (Output Current) and ESR of an output capacitor are shown below. The stable region is marked as the hatched area in the graph. Measurement conditions: Frequency Band: 10Hz to 2MHz, Temperature: -40°C to +85°C.







Ordering Information (Note 13)



Device	Device	Output	Package		7" Tape and Reel		
Without Discharge	With Discharge	Voltage	Code	Package	Quantity	Part Number Suffix	
AP7350-12CF4-7	AP7350D-12CF4-7	1.2	CF4	X2-WLB0606-4	3,000/Tape & Reel	-7	
AP7350-15CF4-7	AP7350D-15CF4-7	1.5	CF4	X2-WLB0606-4	3,000/Tape & Reel	-7	
AP7350-18CF4-7	AP7350D-18CF4-7	1.8	CF4	X2-WLB0606-4	3,000/Tape & Reel	-7	
AP7350-185CF4-7	AP7350D-185CF4-7	1.85	CF4	X2-WLB0606-4	3,000/Tape & Reel	-7	
AP7350-23CF4-7	AP7350D-23CF4-7	2.3	CF4	X2-WLB0606-4	3,000/Tape & Reel	-7	
AP7350-25CF4-7	AP7350D-25CF4-7	2.5	CF4	X2-WLB0606-4	3,000/Tape & Reel	-7	
AP7350-27CF4-7	AP7350D-27CF4-7	2.7	CF4	X2-WLB0606-4	3,000/Tape & Reel	-7	
AP7350-28CF4-7	AP7350D-28CF4-7	2.8	CF4	X2-WLB0606-4	3,000/Tape & Reel	-7	
AP7350-30CF4-7	AP7350D-30CF4-7	3.0	CF4	X2-WLB0606-4	3,000/Tape & Reel	-7	
AP7350-33CF4-7	AP7350D-33CF4-7	3.3	CF4	X2-WLB0606-4	3,000/Tape & Reel	-7	
AP7350-45CF4-7	AP7350D-45CF4-7	4.5	CF4	X2-WLB0606-4	3,000/Tape & Reel	-7	

Note: 13. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information

(1) X2-WLB0606-4

(Top View)

• X Y W X or \overline{X} : Identification Code

Y: Year: 0~9

W : Week : A~Z : 1~26 week; a~z : 27~52 week; z represents

52 and 53 week

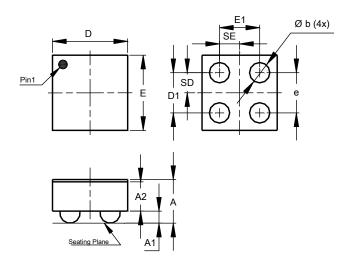
Part Number	Vout	Package	Identification Code
AP7350-12CF4-7	1.2V	X2-WLB0606-4	A
AP7350-15CF4-7	1.5V	X2-WLB0606-4	В
AP7350-18CF4-7	1.8V	X2-WLB0606-4	С
AP7350-185CF4-7	1.85V	X2-WLB0606-4	R
AP7350-23CF4-7	2.3V	X2-WLB0606-4	9
AP7350-25CF4-7	2.5V	X2-WLB0606-4	D
AP7350-27CF4-7	2.7V	X2-WLB0606-4	\overline{A}
AP7350-28CF4-7	2.8V	X2-WLB0606-4	E
AP7350-30CF4-7	3.0V	X2-WLB0606-4	F
AP7350-33CF4-7	3.3V	X2-WLB0606-4	G
AP7350-45CF4-7	4.5V	X2-WLB0606-4	7
AP7350D-12CF4-7	1.2V	X2-WLB0606-4	Н
AP7350D-15CF4-7	1.5V	X2-WLB0606-4	J
AP7350D-18CF4-7	1.8V	X2-WLB0606-4	К
AP7350D-185CF4-7	1.85V	X2-WLB0606-4	S
AP7350D-23CF4-7	2.3V	X2-WLB0606-4	9
AP7350D-25CF4-7	2.5V	X2-WLB0606-4	L
AP7350D-27CF4-7	2.7V	X2-WLB0606-4	B
AP7350D-28CF4-7	2.8V	X2-WLB0606-4	M
AP7350D-30CF4-7	3.0V	X2-WLB0606-4	N
AP7350D-33CF4-7	3.3V	X2-WLB0606-4	Р
AP7350D-45CF4-7	4.5V	X2-WLB0606-4	8



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-WLB0606-4

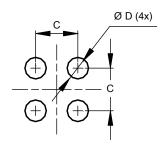


X2-WLB0606-4				
Dim	Min	Max	Тур	
Α	0.300	0.380	0.340	
A1	0.075	0.105	0.090	
A2	0.205	0.255	0.230	
b	0.110	0.190	0.150	
D	0.625	0.655	0.640	
D1	0.300	0.400	0.350	
Е	0.625	0.655	0.640	
E1	0.300	0.400	0.350	
е	0.350 BSC			
SD	0.175 BSC			
SE	0.175 BSC			
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

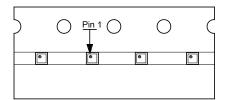
X2-WLB0606-4



Dimensions	Value (in mm)	
С	0.350	
D	0.150	

Tape Orientation

The taping orientation of the other package type can be found on our website at https://www.diodes.com/assets/Packaging-Support-Docs/Ap02007.pdf.





IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2020, Diodes Incorporated

www.diodes.com